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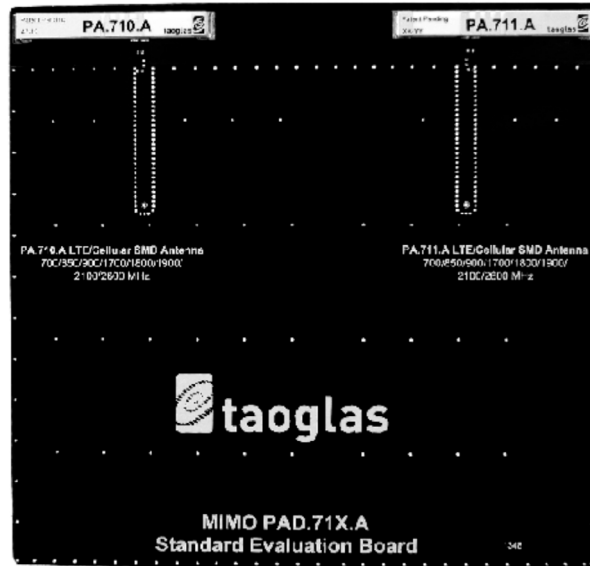
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PA.711.A

Specification Patent Pending

Part No.	PAD.71X.A
Product Name	GEMINI EMBEDDED LTE MIMO 2*2 ANTENNA with PA.710.A and PA.711.A Antennas For 2G/3G/4G 2x2 MIMO systems applications LTE/GSM/CDMA/DCS/PCS/WCDMA/UMTS/HSPA/GPRS/EDGE/IMT 698MHz to 960MHz, 1710MHz to 2690Mhz
Feature	Highest Efficiency Wide-band Embedded MIMO Antenna >40% on all 2G/3G/4G Bands <0.3 ECC on all bands Patent pending SMA(F) Connectors Surface Mount Technology 120.0 x 125.0 x 0.75 mm RoHS Compliant



1. Introduction

The Gemini LTE MIMO 2*2 Embedded Antenna is the only compact MIMO antenna solution for the world LTE M2M and Internet of Things (IOT) market of today. Gemini has two antenna elements, the existing PA.710 LTE MIMO ceramic antenna successfully used in many LTE MIMO devices today, along with its new brother the PA.711 LTE MIMO ceramic antenna. By altering the radiation pattern of the PA.711 to that of the PA.710 (similar to reflecting), Taoglas has created the world's first high efficiency MIMO embedded wide-band cellular antenna conforming to an envelope correlation coefficient of below 0.3. This minimal self interference is critical to achieve high data rates in today's advanced LTE systems.

The patent pending antenna is ideal for integration into high data throughput devices which depend on high efficiency MIMO antennas. Typical applications:

- Intelligent Transport Systems
- High Definition Video Broadcast Systems
- Wireless LTE MIMO M2M devices with legacy 2G/3G Functionality

Antenna board size, dimensions and antenna placement have all been carefully evaluated for optimum performance. It is not recommended to go below this antenna board dimensions, as efficiency will reduce dramatically along with poor isolation. The antennas may also need to be re-tuned to fit into different custom enclosures. Taoglas offers full customization of the antenna system for your device.

Alternatively, PA.710 and PA.711 can be integrated directly on your main board, provided that you follow strict guidelines on meeting minimum main-board ground plane dimensions, transmission line design, matching, and placement of antennas.

Contact Taoglas regional sales office for support.

2. Specifications

ELECTRICAL				
ANTENNA	PA.710 and PA.711			
STANDARD	2G/3G/4G			
Operation Frequency (MHz)	698~960MHz	1710~2170MHz	2300~2400MHz	2490~2690MHz
Peak Gain	1.0dBi	3.0dBi	3.5dBi	2.8dBi
Average Gain	-2.7 dB	-2.6 dB	-2.5dB	-2.2dB
Efficiency	53%	54%	55%	60%
VSWR	<3.5:1			
Impedance	50Ω			
Polarization	Linear			
Radiation Properties	Omni-directional			
Max Input Power	5 W			

- The PA.710 and PA.711 antennas performance were measured with 106x125mm ground plane.

MECHANICAL	
Dimensions (mm)	106x125.0x0.75 mm
Material	FR4
Termination	Ag (environmental-friendly Pb free)
EVB Connector	SMA(F)
ENVIRONMENTAL	
Operation Temperature	-40°C to 85°C
Storage Temperature	-40°C to 105°C
Relative Humidity	Non-condensing 65°C 95% RH
RoHs Compliant	Yes

3. Test Set Up

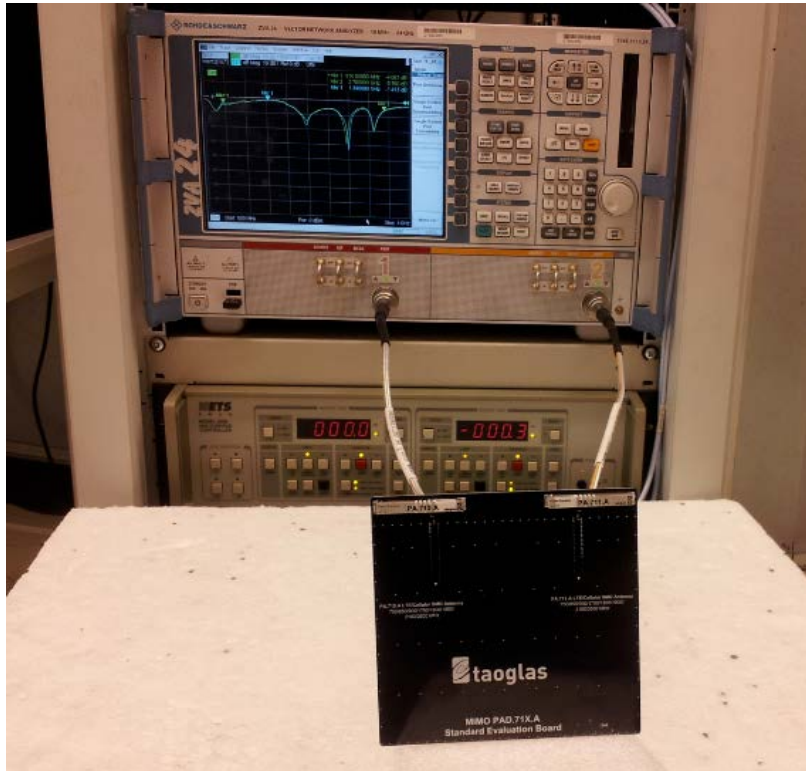


Figure 1. Return Loss and VSWR test set up

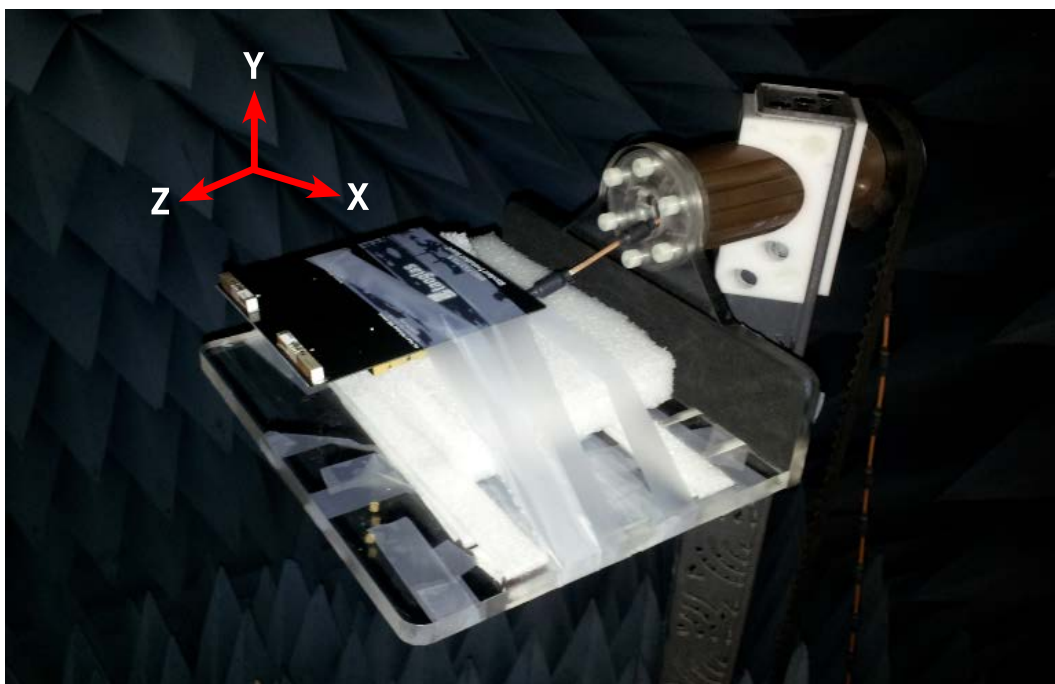


Figure 2. OTA test set up

4. Antenna Parameters

4.1. Return Loss

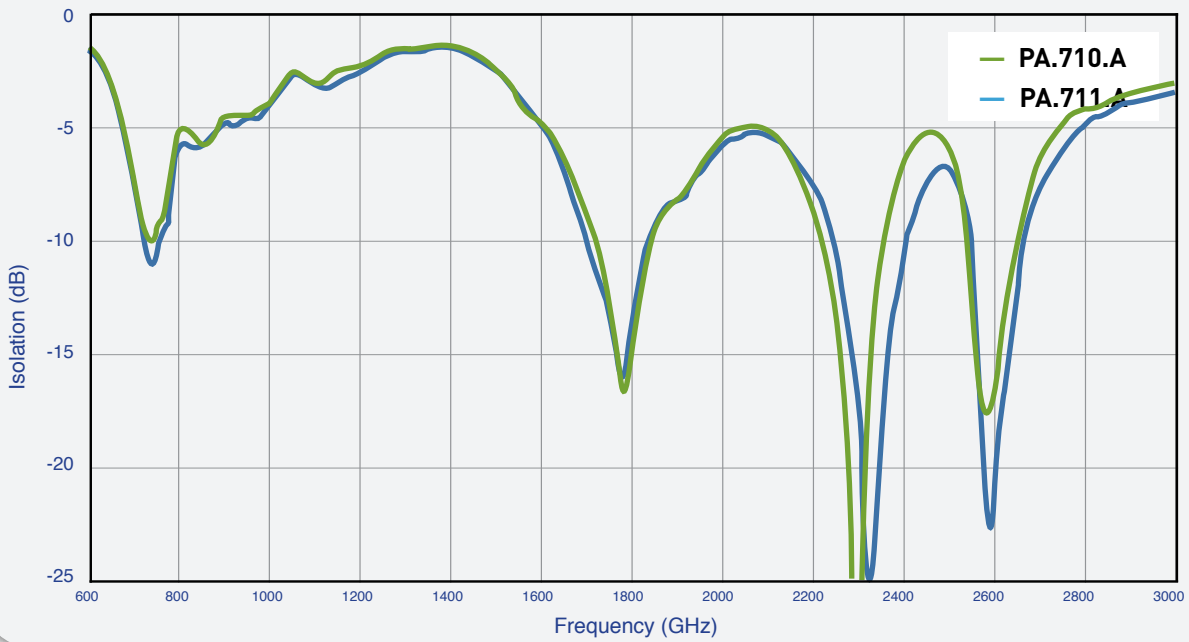


Figure 3. Return Loss of the PA.710 and PA.711 antennas

4.2. VSWR

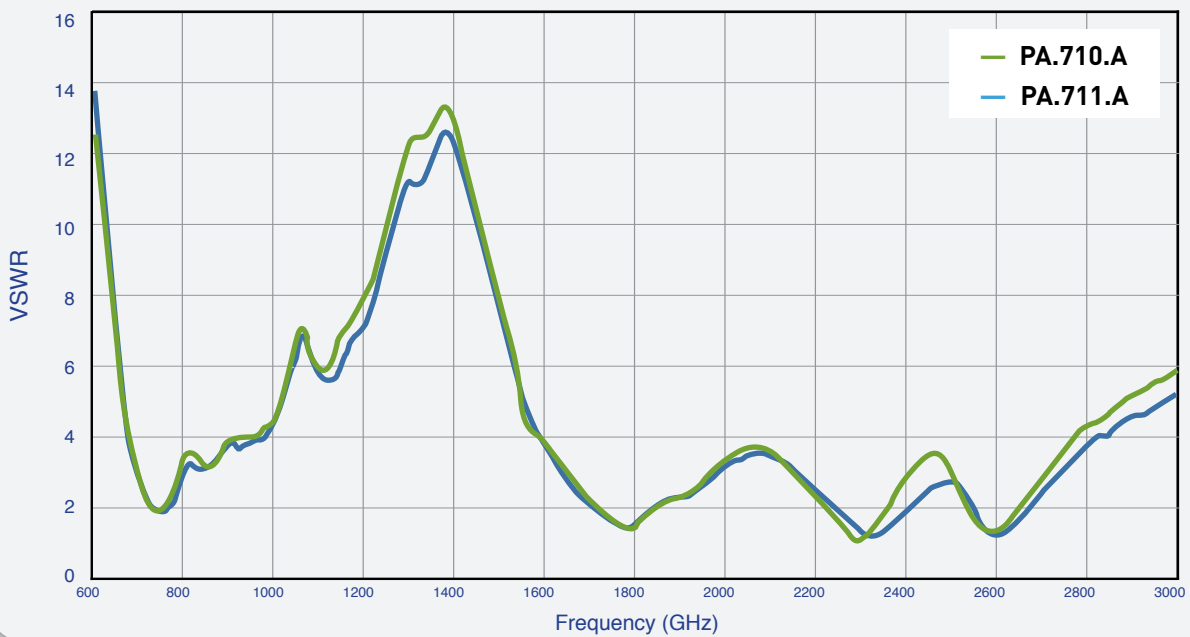


Figure 4. VSWR of the PA.710 and PA.711 antennas

4.3. Isolation

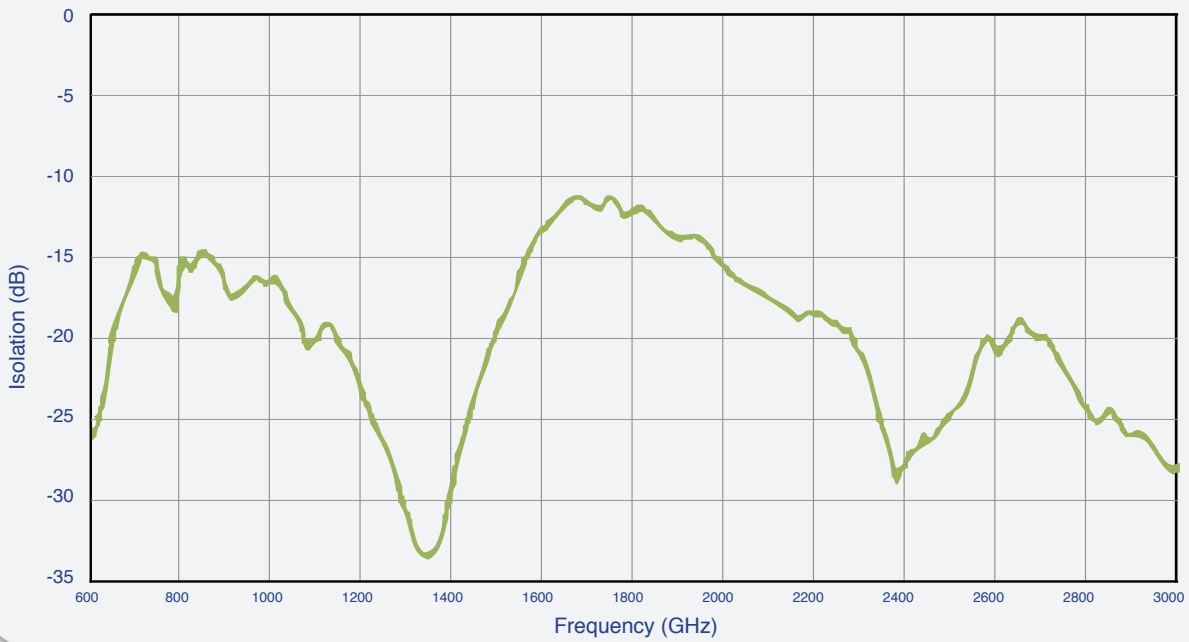


Figure 5. Isolation of the PA.710 and PA.711 antennas

4.4. Envelope Correlation Coefficient

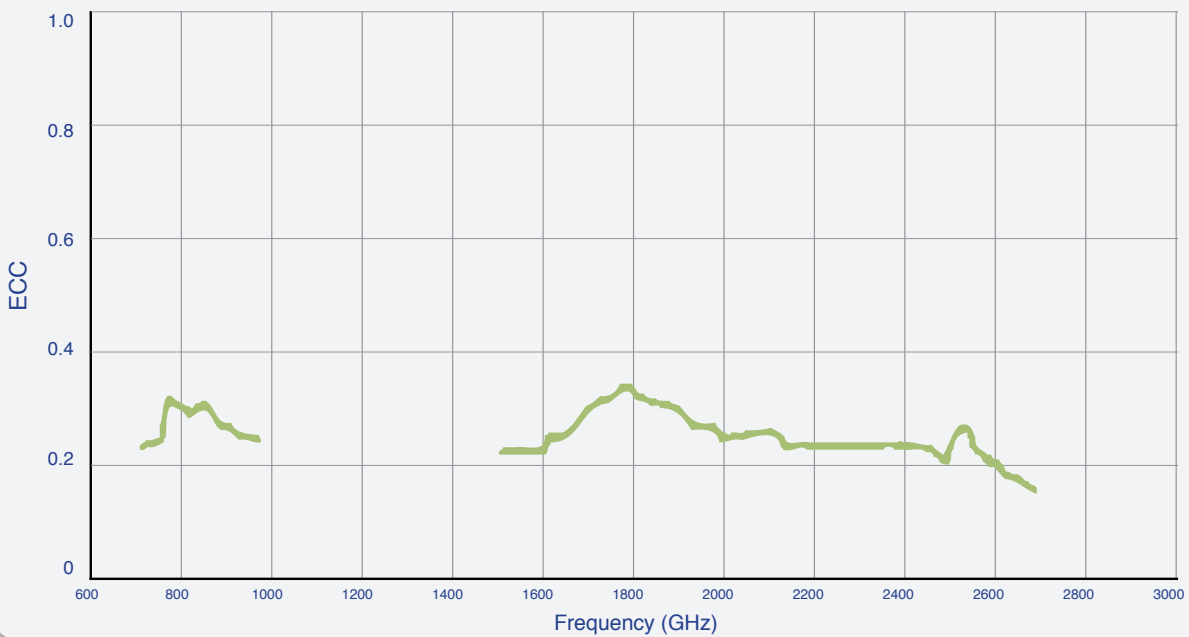


Figure 6. ECC of the PA.710 and PA.711 antennas

4.5. Efficiency

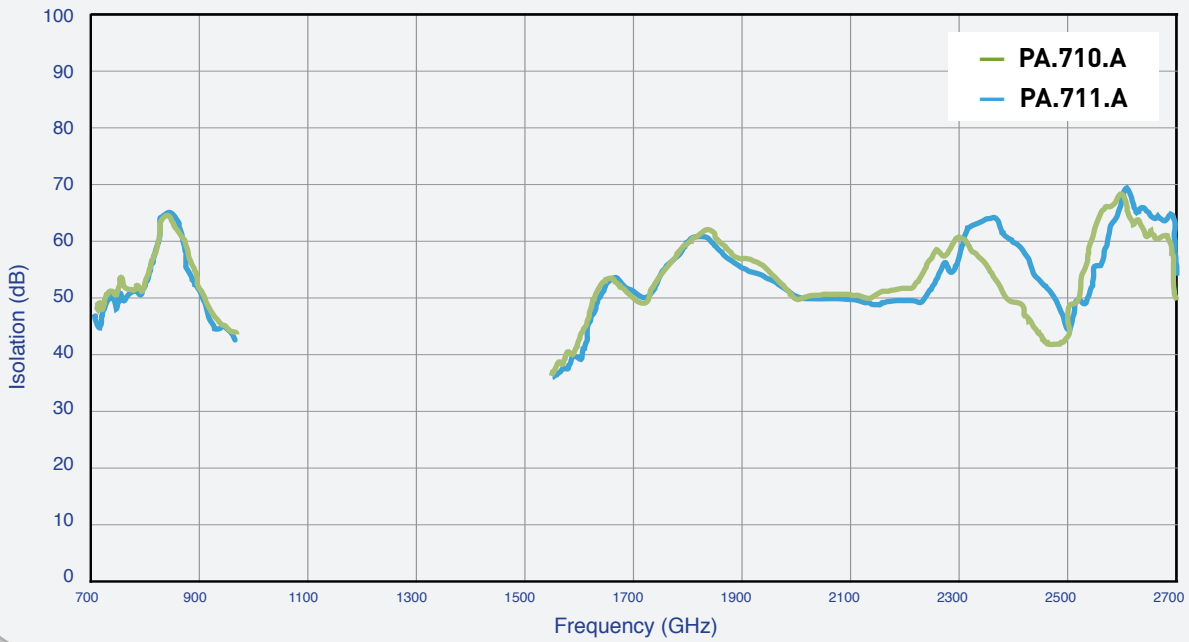


Figure 7. Efficiency of the PA.710 and PA.711 antennas

4.6. Peak Gain

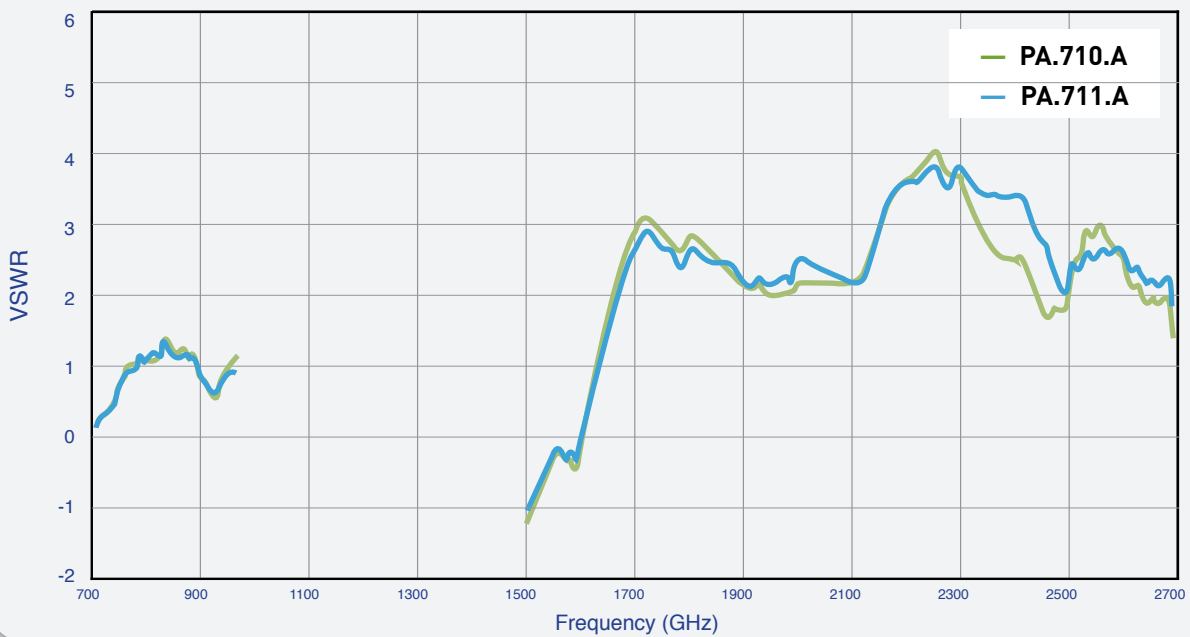


Figure 8. Peak Gain of the PA.710 and PA.711 antennas

4.7. Average Gain

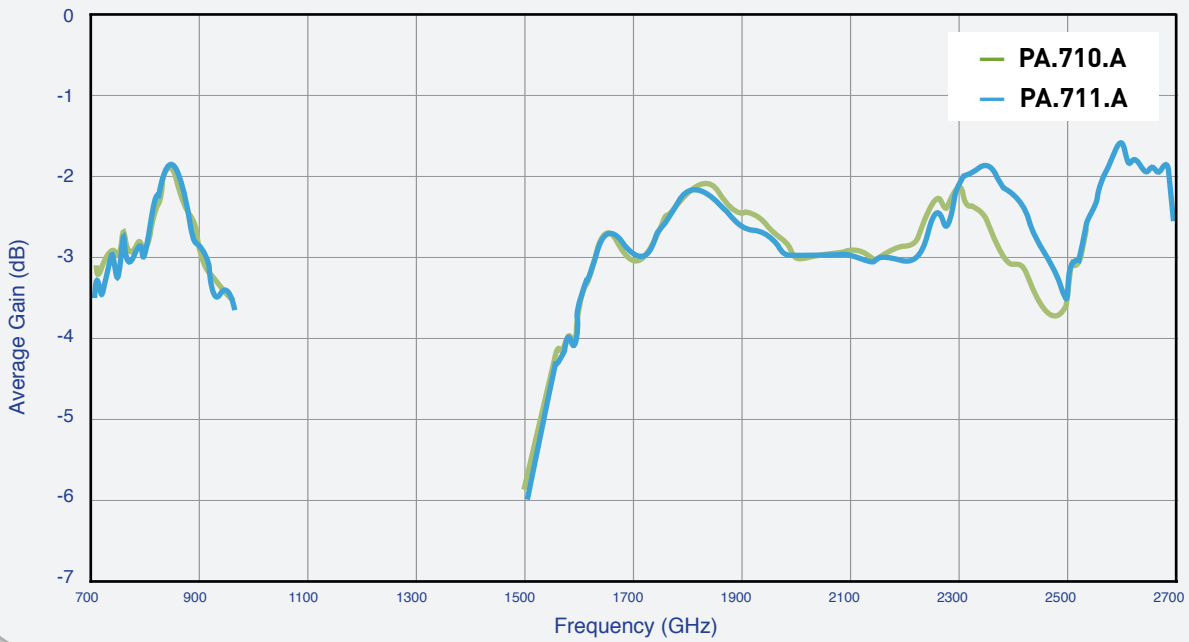


Figure 9. Average Gain of the PA.710 and PA.711 antennas

4.8. 3D Radiation Pattern (measured on 120*125mm EVB)

Azimuth = 0.0
Elevation :
Roll = -45.

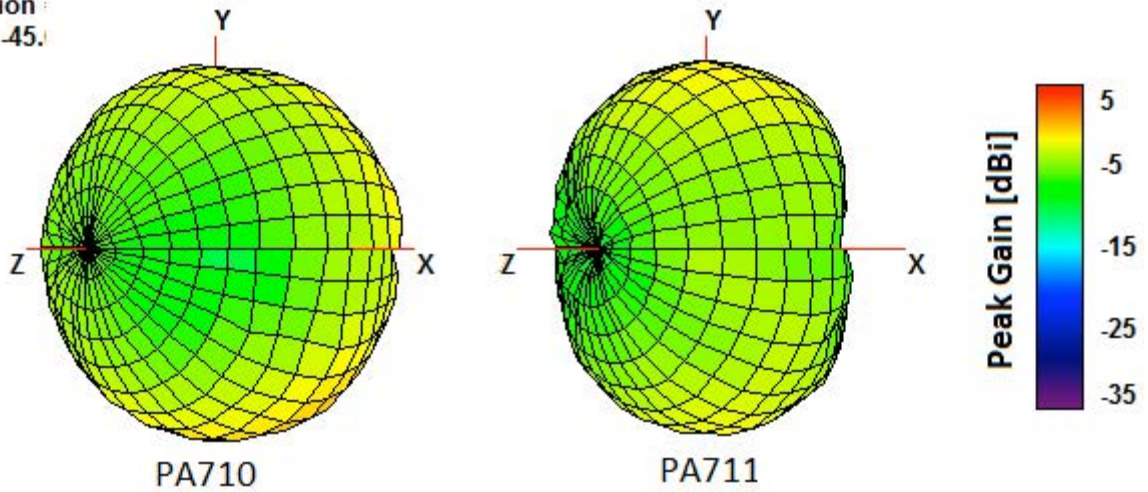


Figure 10. 3D Radiation Pattern at 700MHz of the PA.710 and PA.711 antennast

Azimuth = 0.0
Elevation
Roll = -45.

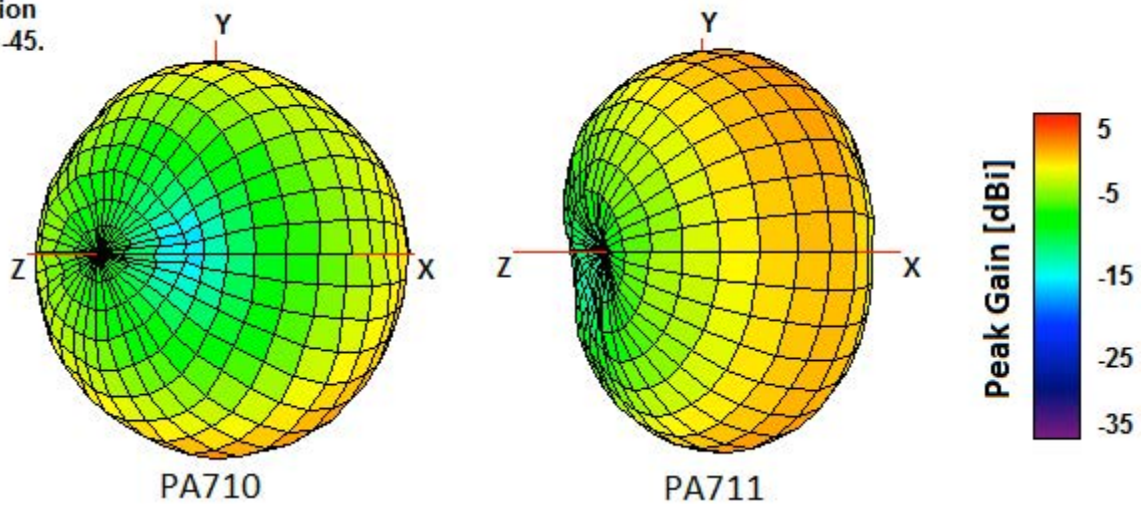


Figure 11. 3D Radiation Pattern at 800MHz of the PA.710 and PA.711 antennas

Azimuth = 0.0
Elevation
Roll = -45.

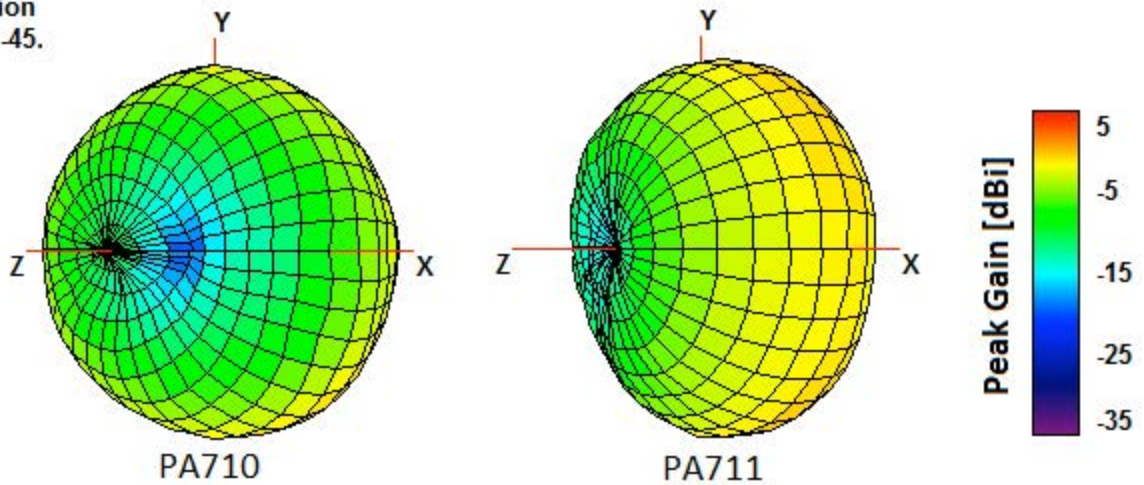


Figure 12. 3D Radiation Pattern at 900MHz of the PA.710 and PA.711 antennas

Azimuth = 0.0
Elevation
Roll = -45.

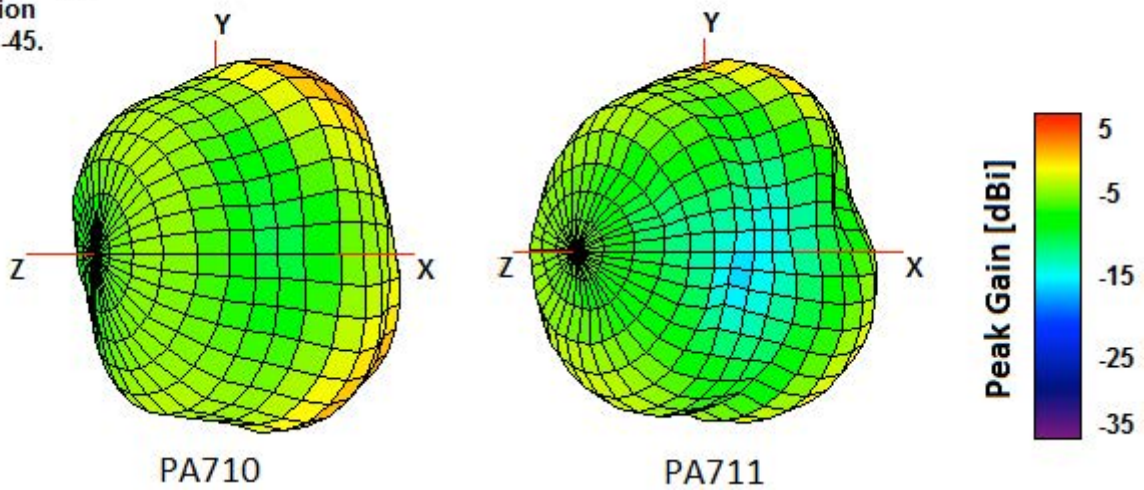


Figure 13. 3D Radiation Pattern at 1710MHz of the PA.710 and PA.711 antennas

Azimuth = 0.0
Elevation
Roll = -45.

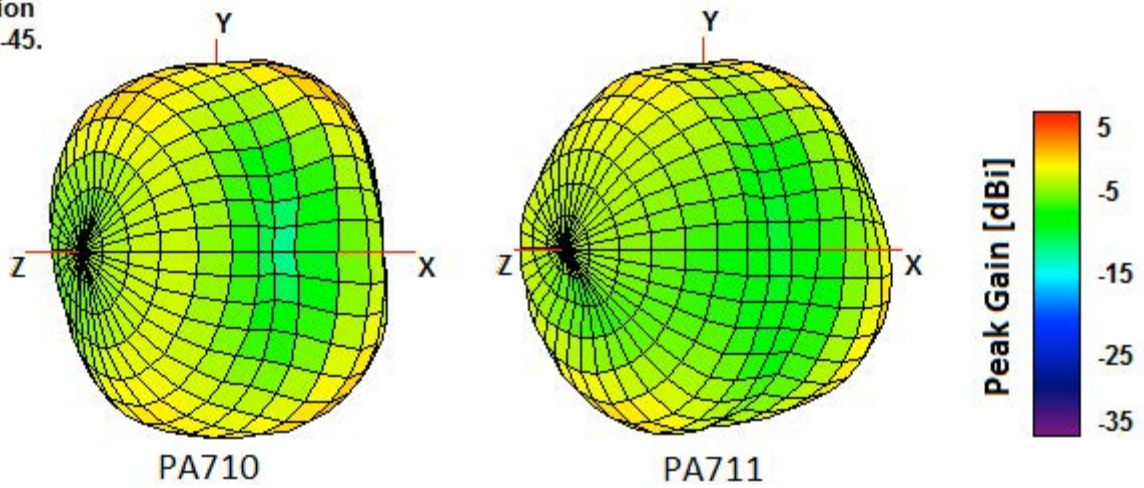


Figure 14. 3D Radiation Pattern at 1805MHz of the PA.710 and PA.711 antennas

Azimuth = 0.0
Elevation
Roll = -45.

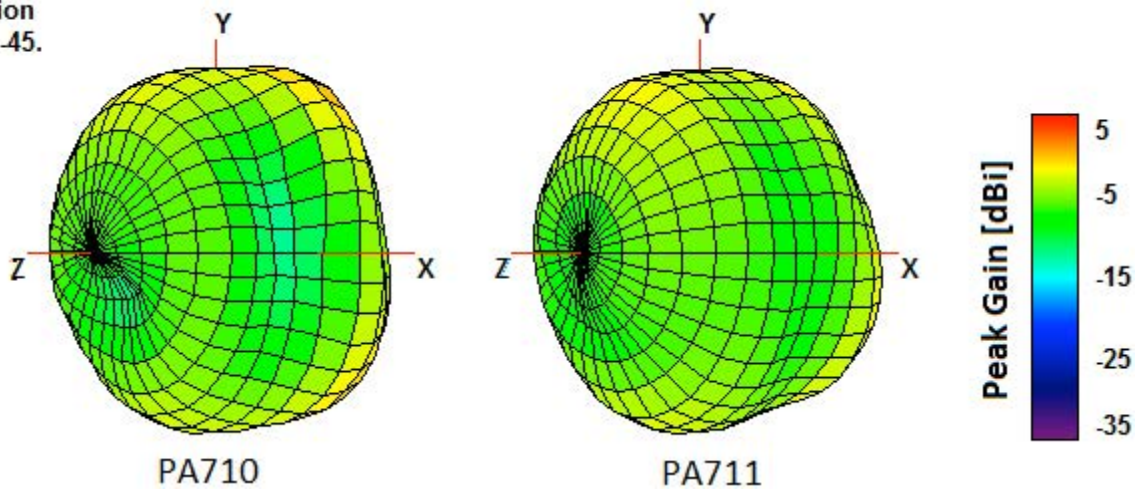


Figure 15. 3D Radiation Pattern at 1910MHz of the PA.710 and PA.711 antennas

Azimuth = 0.0
Elevation
Roll = -45.

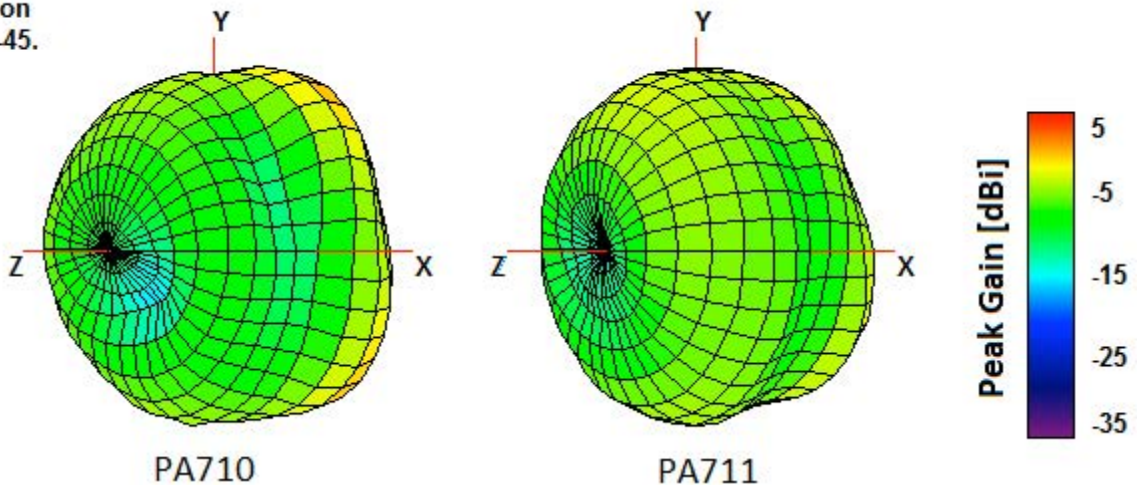


Figure 16. 3D Radiation Pattern at 1990MHz of the PA.710 and PA.711 antennast

Azimuth = 0.0
Elevation
Roll = -45.

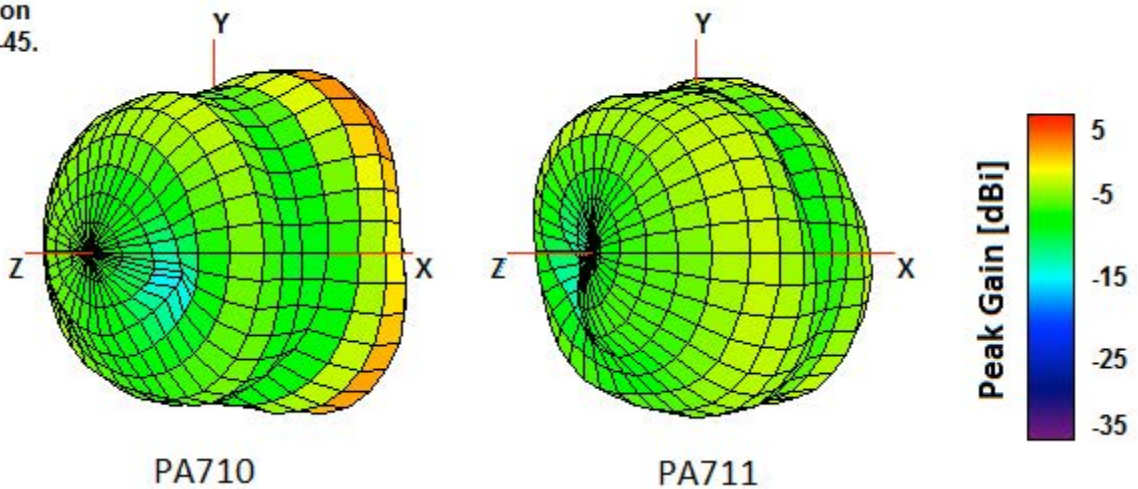


Figure 17. 3D Radiation Pattern at 2170MHz of the PA.710 and PA.711 antennas

Azimuth = 0.0
Elevation
Roll = -45.

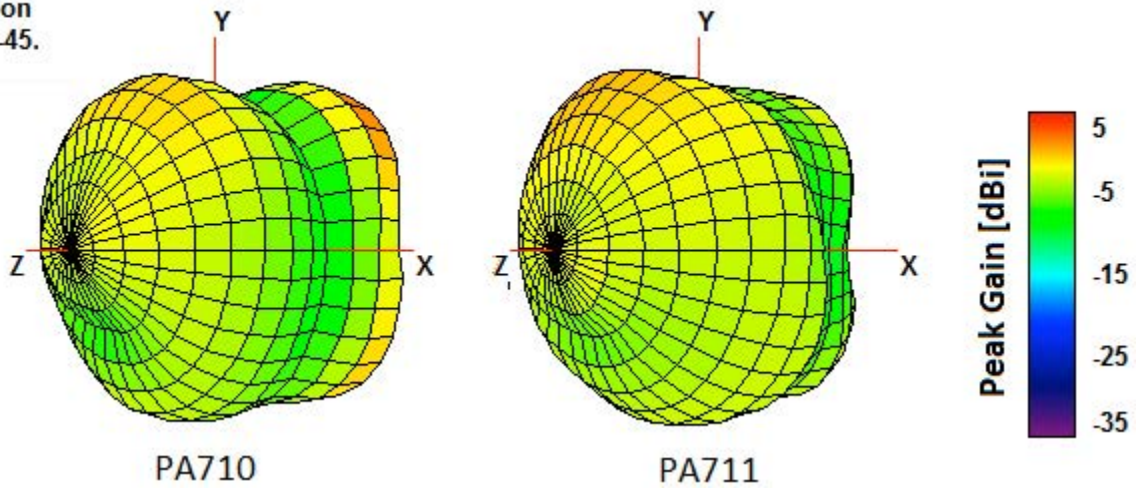


Figure 18. 3D Radiation Pattern at 2400MHz of the PA.710 and PA.711 antennas

Azimuth = 0.0
Elevation
Roll = -45.

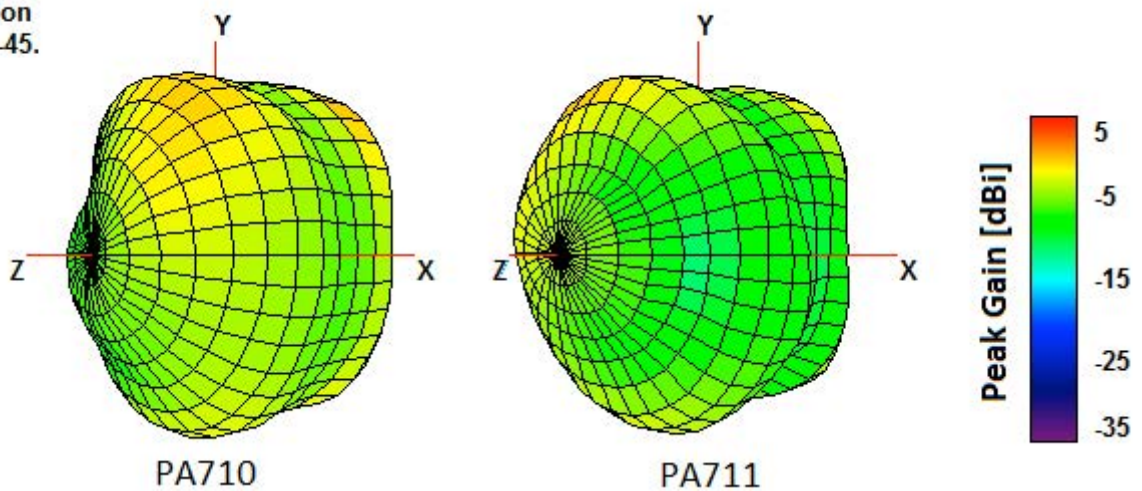


Figure 19. 3D Radiation Pattern at 2500MHz of the PA.710 and PA.711 antennas

Azimuth = 0.0
Elevation
Roll = -45.

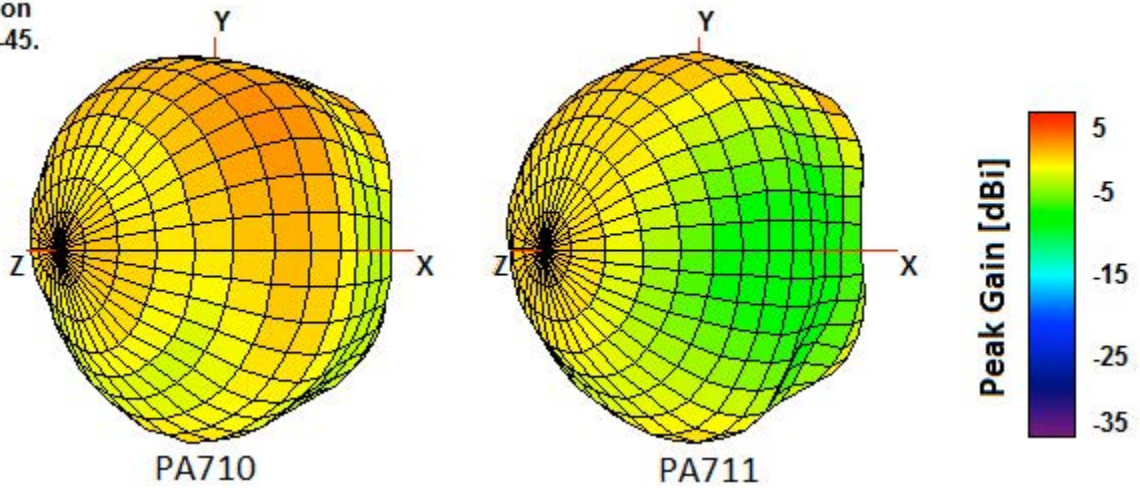


Figure 20. 3D Radiation Pattern at 2600MHz of the PA.710 and PA.711 antennas

Azimuth = 0.0
Elevation
Roll = -45.

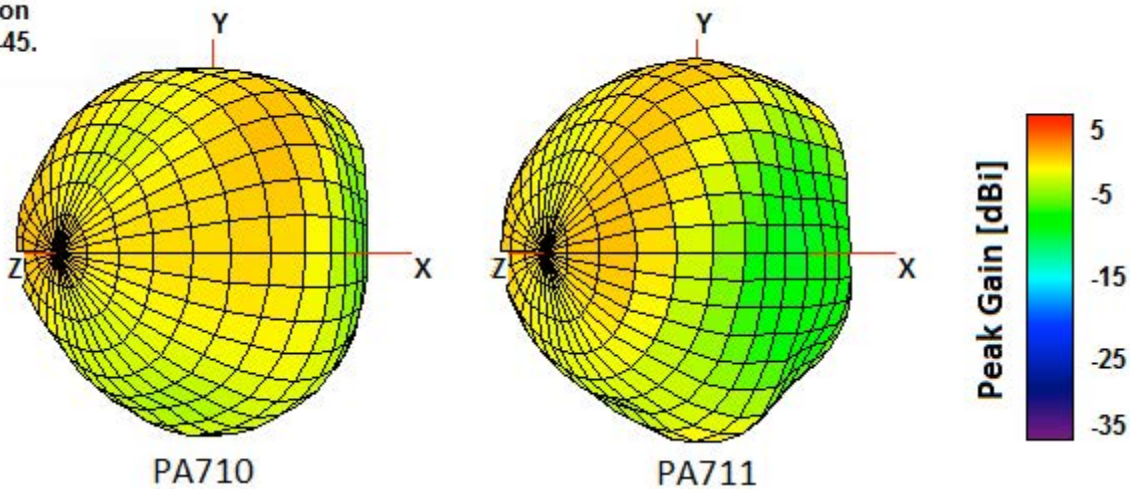


Figure 21. 3D Radiation Pattern at 2700MHz of the PA.710 and PA.711 antennas

4.9. PA.710 2D Radiation Pattern (measured on 120*125mm EVB)

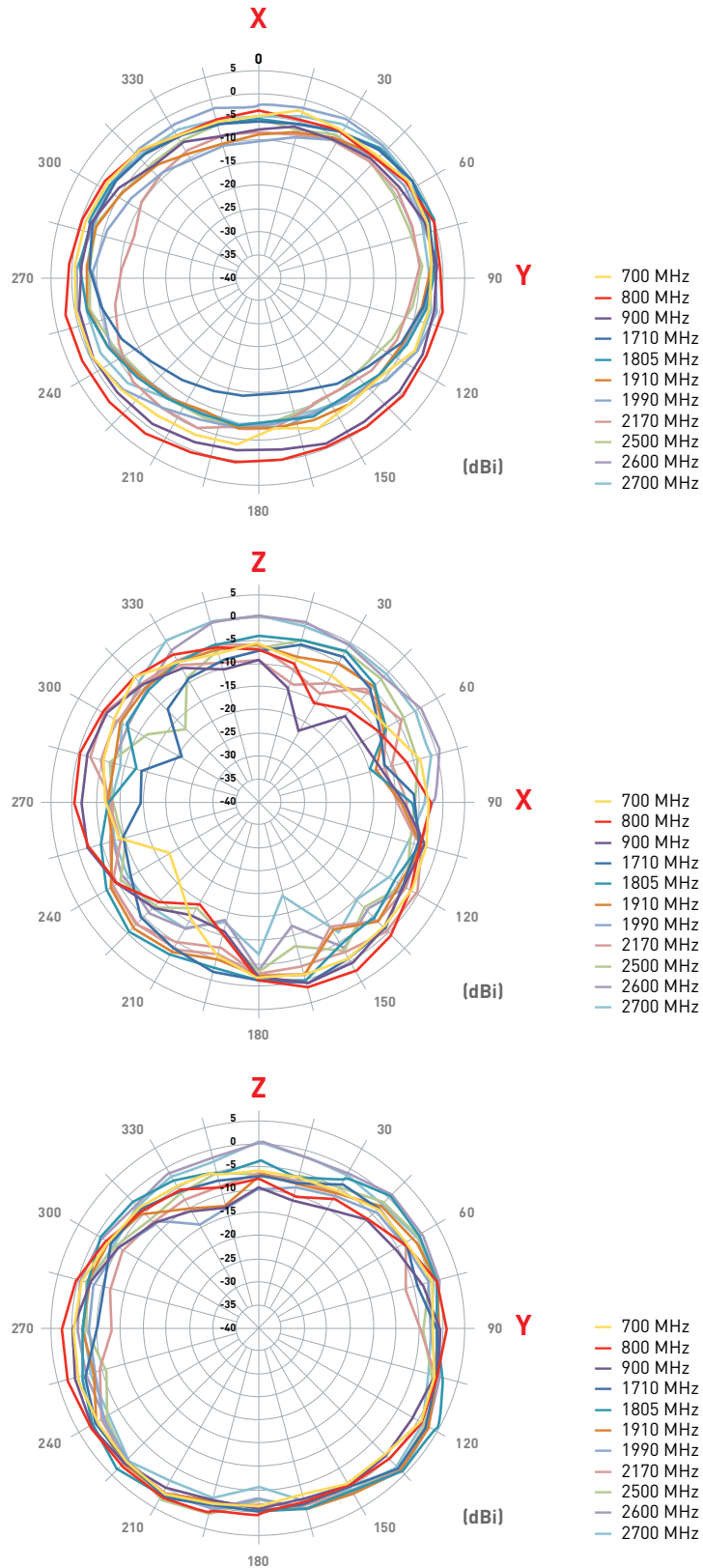


Figure 22. 2D Radiation Pattern of the PA.710 Antenna

4.10 PA.711 2D Radiation Pattern (measured on 120*45mm EVB)

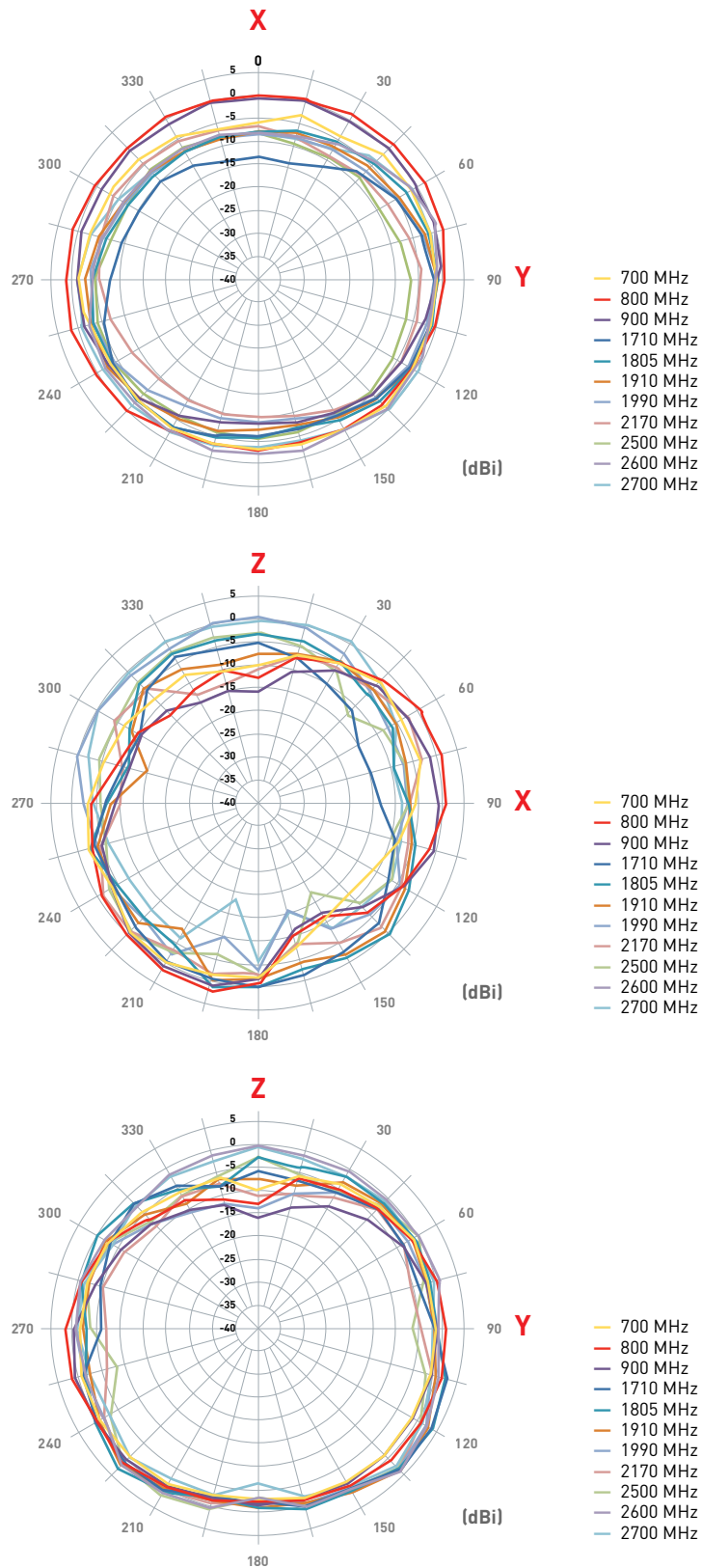


Figure 23. 2D Radiation Pattern of the PA.711 Antenna

5. Mechanical Drawing

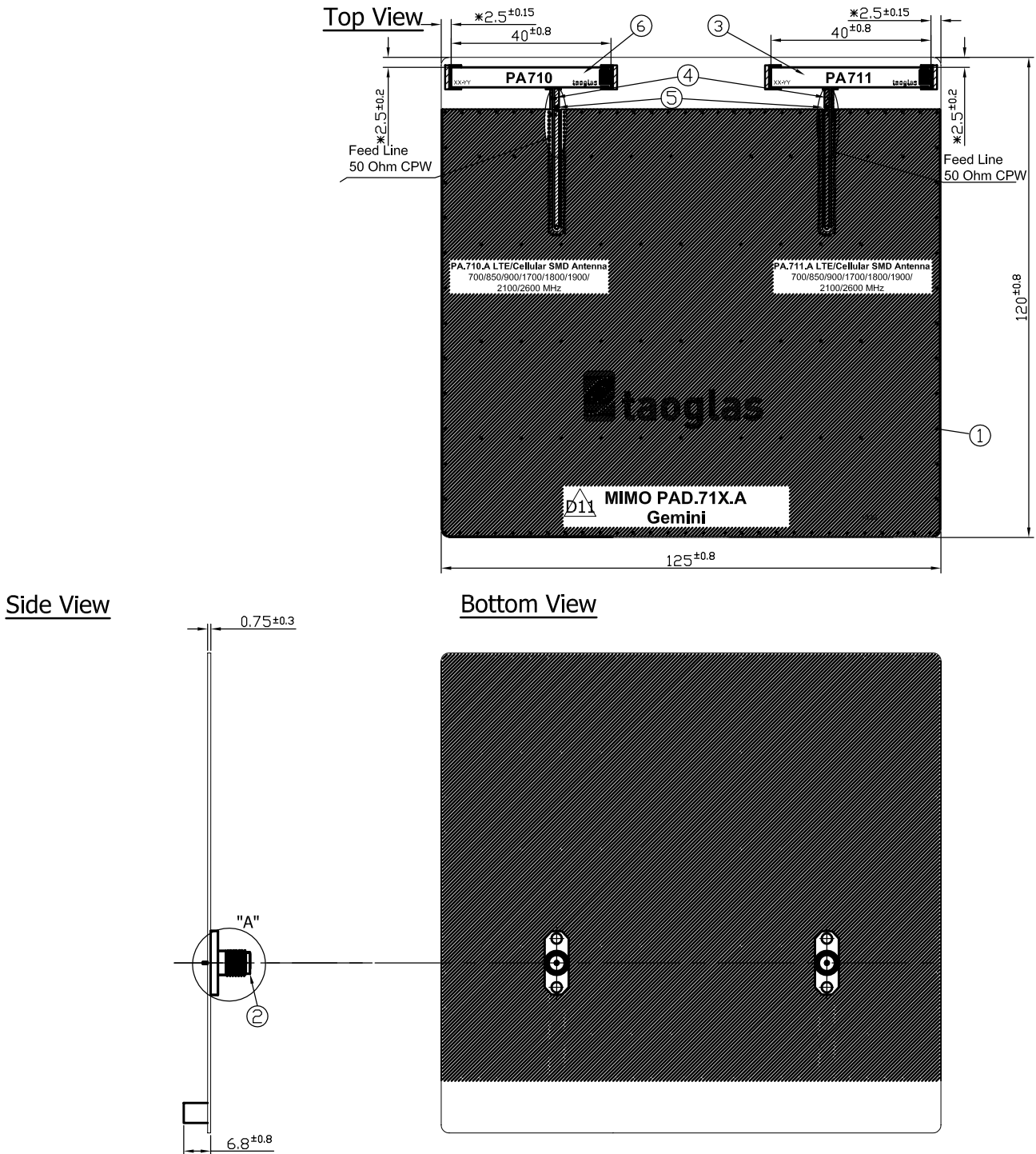


Figure 24. Mechanical drawing of PAD.71x.A

6. Layout Dimensions

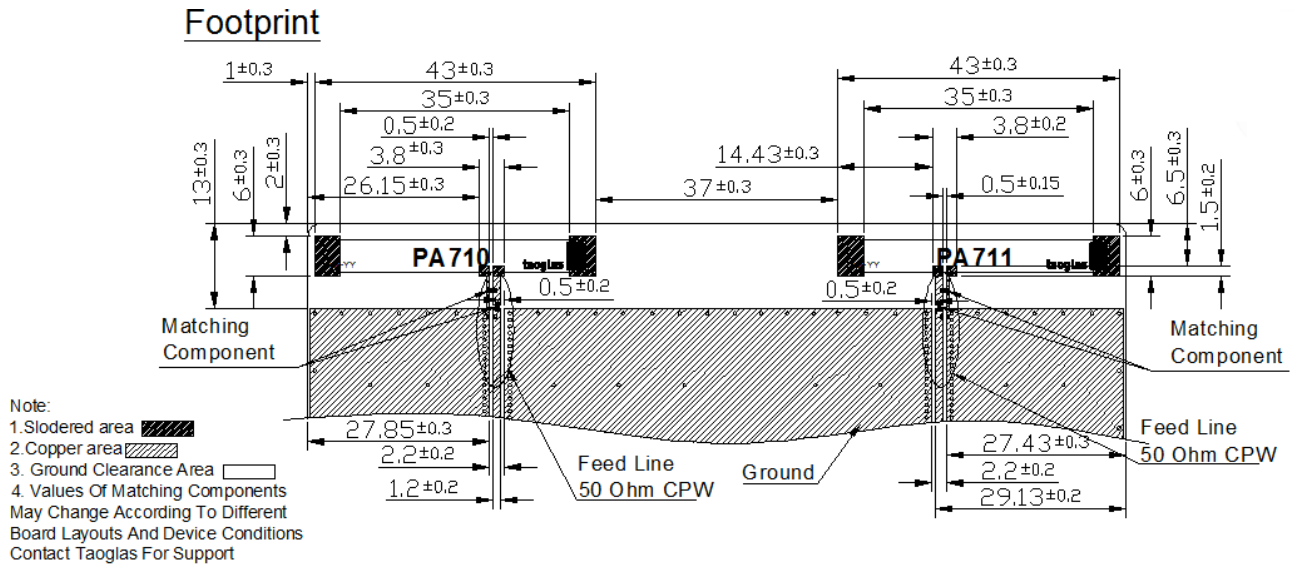
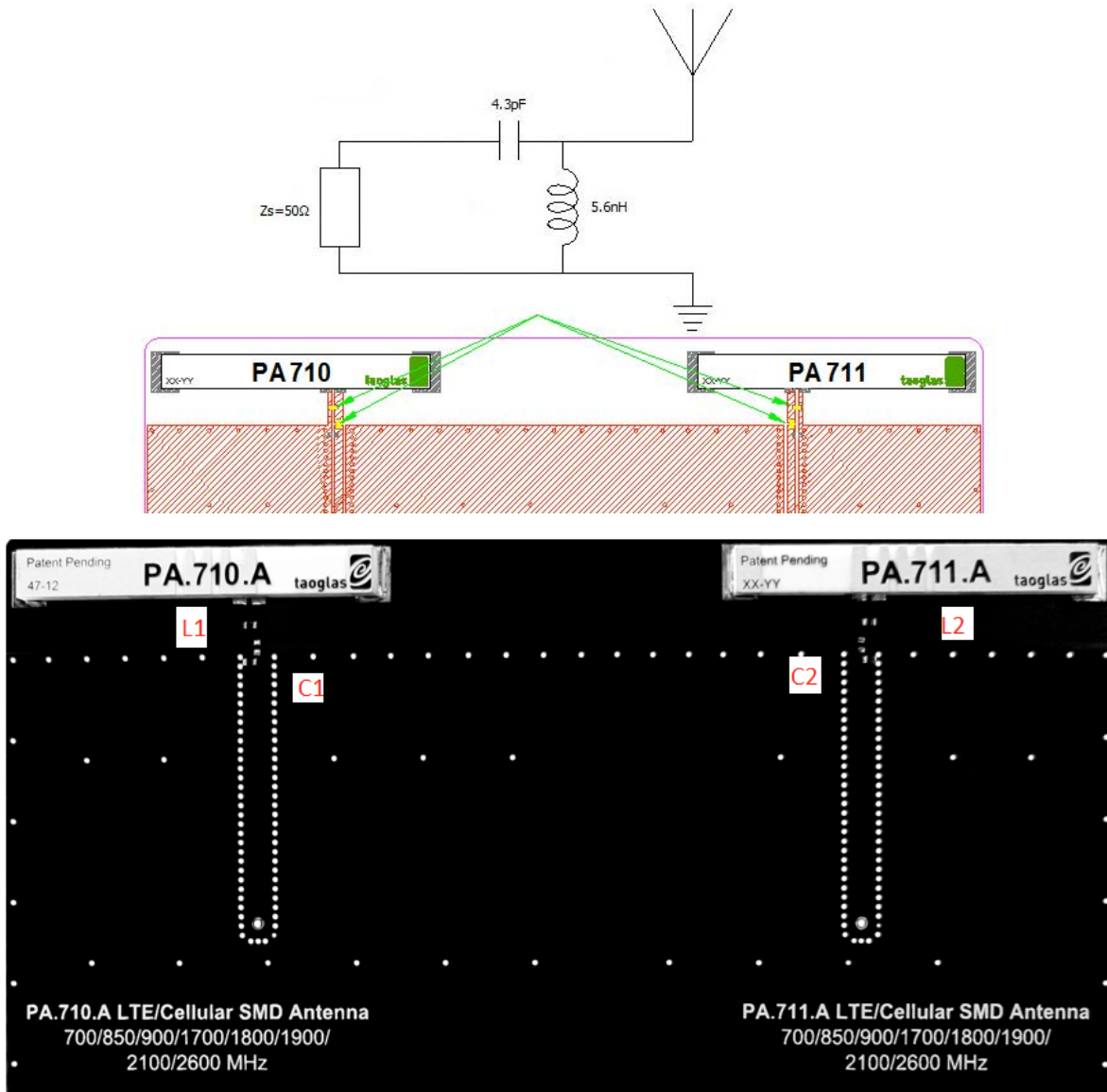


Figure 25. Layout dimensions of PAD.71x.A

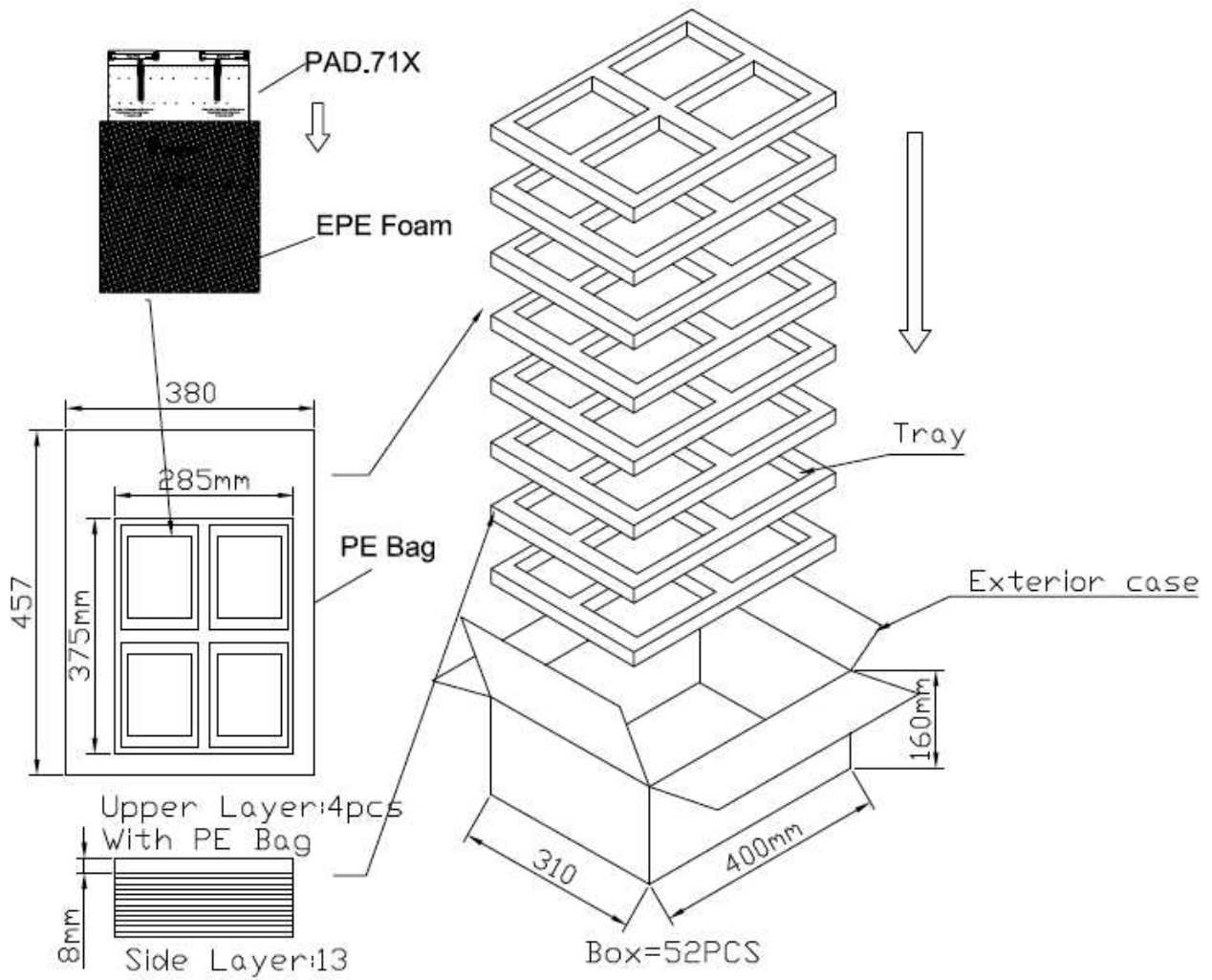
7. Matching Circuit



Circuit Symbol	Size	Description
L1	0402	5.6nH inductor (LQG15HS5N6S02D)
C1	0402	4.3pF Capacitor (GRM1555C1H4R3CA01D)
L2	0402	5.6nH inductor (LQG15HS5N6S02D)
C2	0402	4.3pF Capacitor (GRM1555C1H4R3CA01D)

Figure 26. Recommended matching circuit

8. Packaging



9. Recommended Reflow Temperature Profile

PA.710 and the PA.711 can be assembled following either Sn-Pb or Pb-Free assembly processes. The recommended soldering temperatures are as follows:

Phase	Profile Features	Sn-Pb Assembly	Pb-Free Assembly (SnAgCu)
Ramp-Up	Avg. Ramp-Up Rate (T _{smax} to TP)	3°C/second (max)	3°C/second (max)
Preheat	Temperature Min (T _{smin})	100°	100°
	Temperature Max (T _{smax})	150°	150°
	Time (t _{smin} to t _{smax})	60-120 seconds	60-120 seconds
Reflow	Temperature (TL)	183°C	217°C
	Total Time Above TL b(tL)	60-150 seconds	60-150 seconds
Peak	Temperature (T _p)	235°C	260°C
	Time (t _p)	10-30 seconds	20-40 seconds
Ramp-Down	Rate	6°C/second (max)	6°C/second (max)
Time from 25°C to peak Temperature		6 minutes max	8 minutes max

Temperature profile – (green area) for the assembly process in reflow ovens

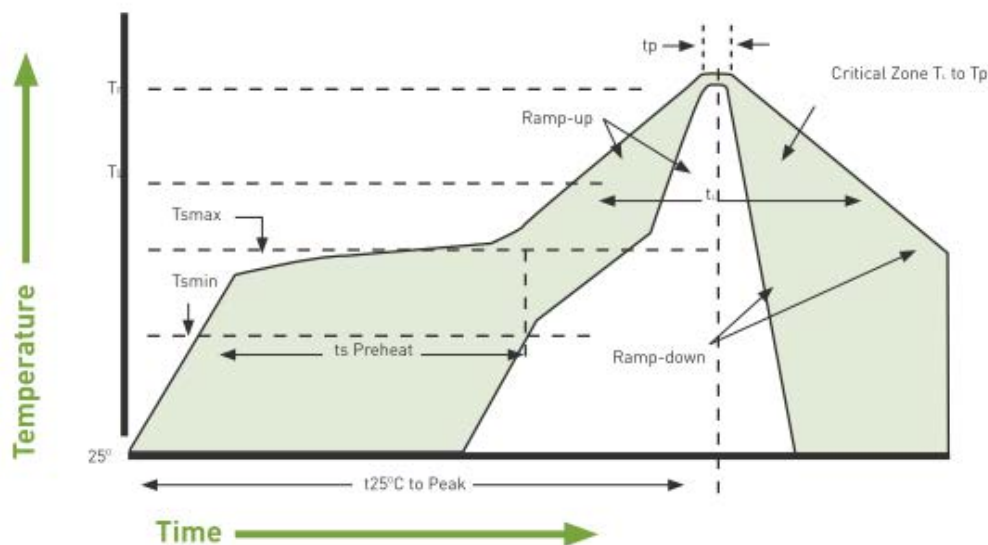


Figure 27. Temperature profile for the assembly process in reflow ovens

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